



Why should you care about JTAG / Boundary Scan / IEEE 1149.x

GOPEL Boundary Scan Seminar

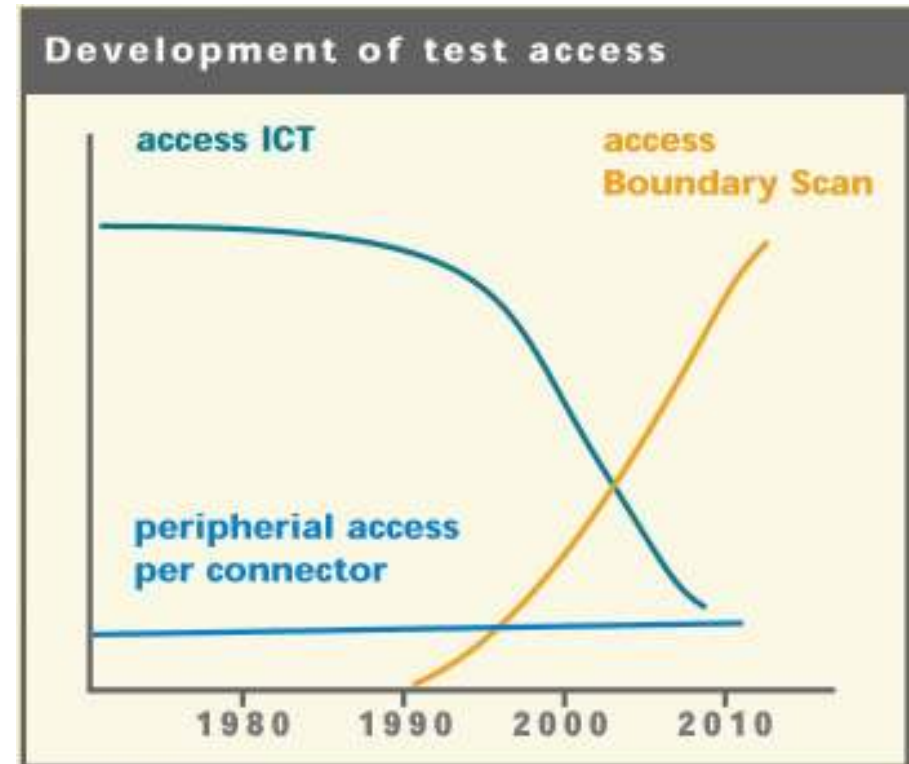
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Why do we need DFT ?

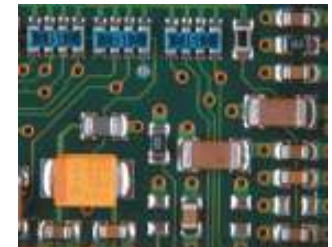
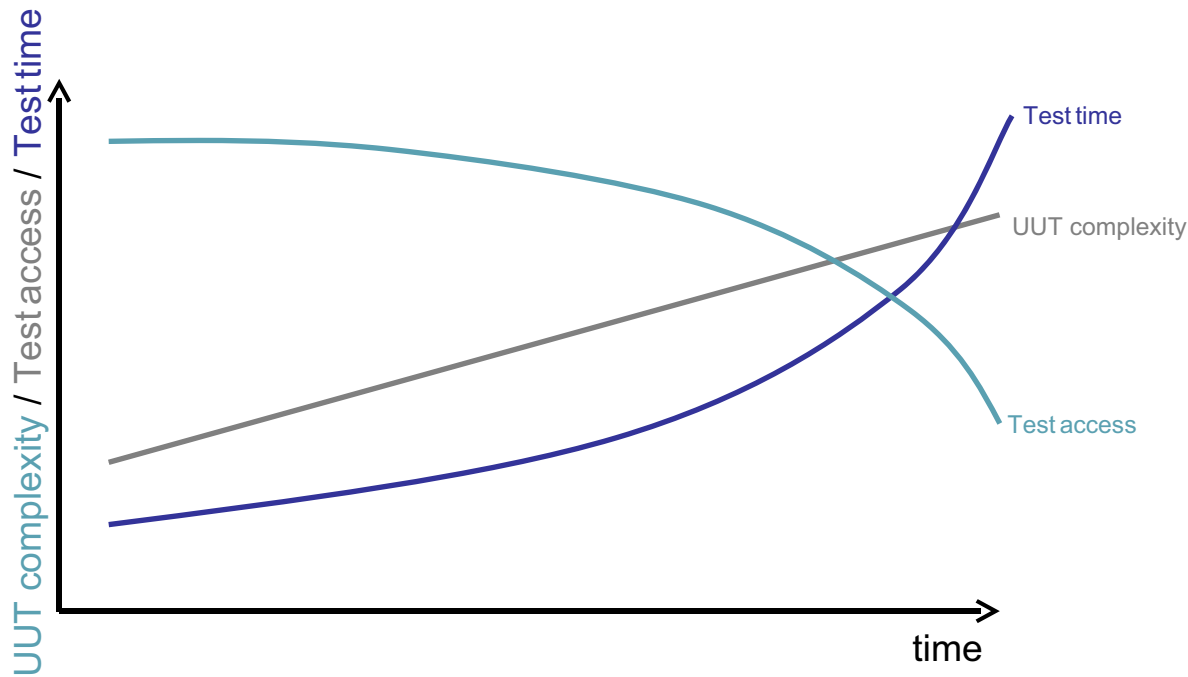
- Shrinking device geometries, device pitch
- New packaging technologies
- Diminishing test access
- Rising UUT complexity
- Rising test time





Test obstacles

- UUT complexity
- Test access
- Test time





UUT complexity

- Highly integrated components
- More functionality on one board
- Reduced testability

And at the same time ...

- Shorter NPI and PLC
- High product mix





Reduced test access

- New device packaging (μ BGA, CSP, COP, ...)
- Passive components embedded in PCB
- Denser board layouts
- Fewer, smaller test points



*Diminishing test access
with probe based test systems*



Cost of Test

- Requirement to lower cost because of
 - Inflation
 - Shorter PLC
 - Smaller profit margins
- Test DOES “add value” by
 - Catching defects
 - Helping control the manufacturing process
 - Reducing field returns and warranty issues



How do we test?

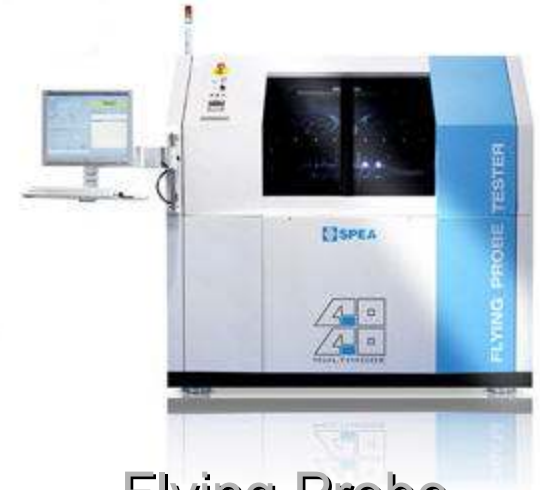
Automated
Optical /
X-Ray
Inspection
(AOI/AXI)



Manufacturing
Defect Analyser
(MDA)



Flying Probe
Test (FPT)



Functional Test
(FT)



Manual Inspection



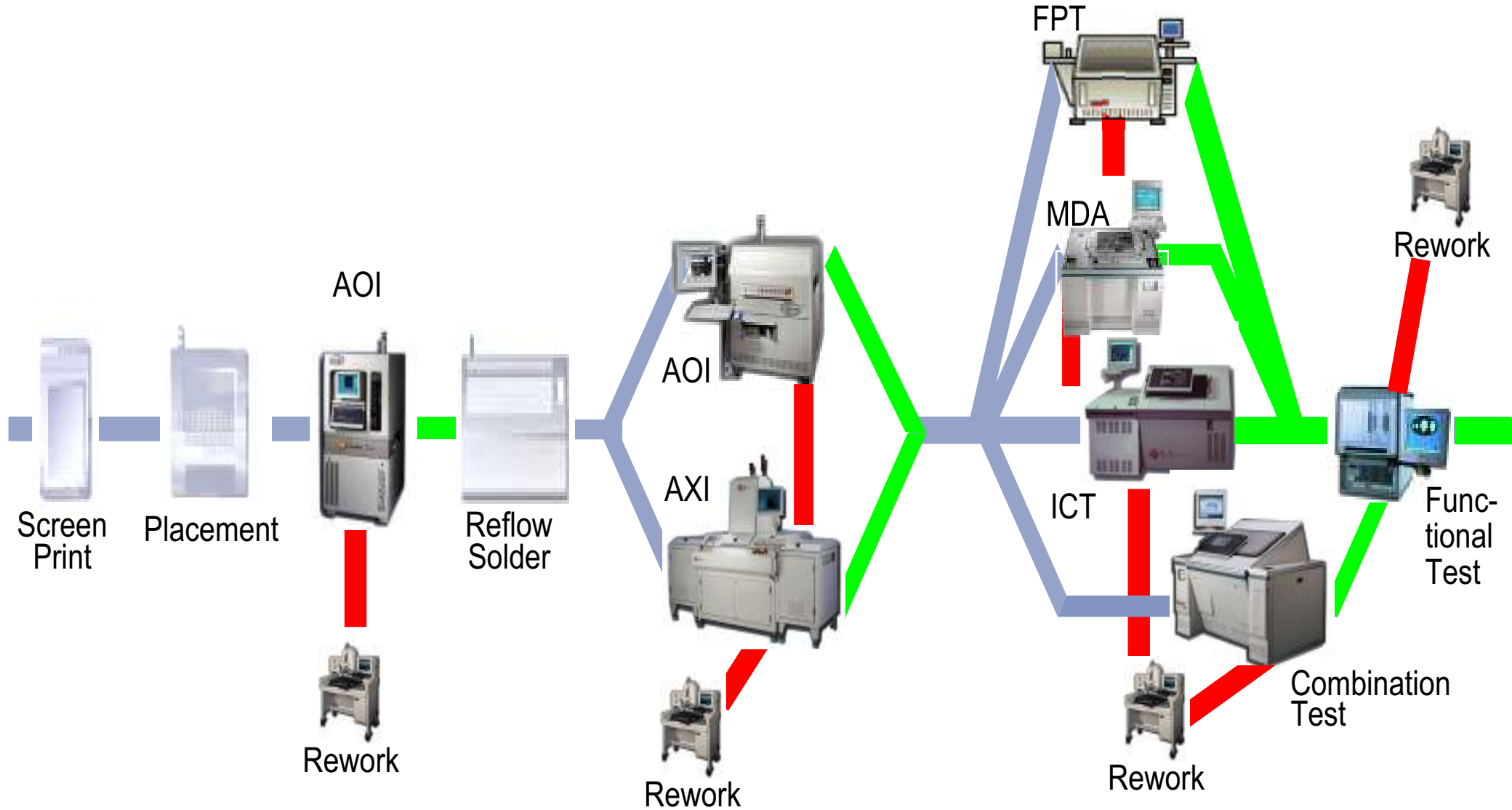
In-Circuit Test
(ICT)

most likely: *a combination of those methods*





Common test solutions





Frequent problems

- High density, small footprint components
(BGA, microBGA, Chip On Board, Chip Scale Packages)
- Loss of test access
- Ballooning Fixture Costs
- Long test development time
- Reduced diagnostic resolution

Is there a way out?





Can Boundary Scan help?

- Regain test access
- Improve time to market
- Use Boundary Scan throughout the whole product life cycle (reuse test applications)
- Supports chip, board, and system level test
- Reduce fixture cost
- Improve diagnostic resolution
- Shorten debug time

Reduce cost of test





Case Study A

Type 1: single PCB, predominantly digital circuits

- components with relatively small pin count, no BGA's;
- Some components with Boundary Scan capabilities;
- well suited for In-Circuit-Test;
- cost saving potential in combination of Boundary Scan with ICT

- **Example:**

- ~ 1200 component leads
- 200 nets
- 3 BScan compliant components
- 54 BScan accessible nets (27%)
- Bed-Of-Nail adapter with 200 nails: about \$5,000 (80% of the total account for nails, or \$4,000)
- reducing the number of nails by 54 (27% of all 200 nets)
⇒ achievable savings: 27% of \$4,000, or \$1,080
- 50 different kinds of such PCB's: **save ~ \$54,000 annually**

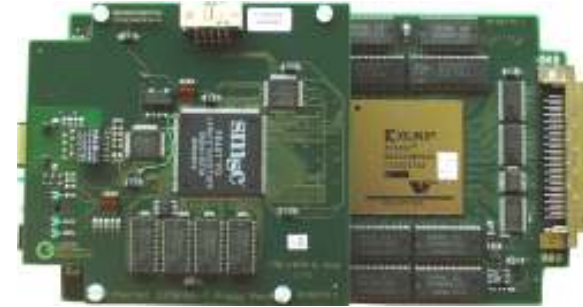




Case Study B

Type 2: single PCB, predominantly digital circuits

- components with high pin count, few BGA's;
- Some components provide Boundary Scan capabilities;
- High product mix, low volume \Rightarrow Flying Prober most useful
- **Example (average unit):**
 - 560 nets, 3200 pins,
 - 2 BScan compliant BGA's (total of 688 Pins),
 - other high-pin components, total of 956 pins,
 - 230 low pin count components;
 - total of 5114 Flying Probe test steps,
13 test steps per second \Rightarrow test time of 6.5 minutes;
 - BScan can eliminate 1937 Flying Probe test steps
(38% of all 5114 steps) \Rightarrow cost saving of \$2.74 per assembly
 - 50,000 PCBs per year \Rightarrow **savings potential is \$137.000 annually**





Case Study C

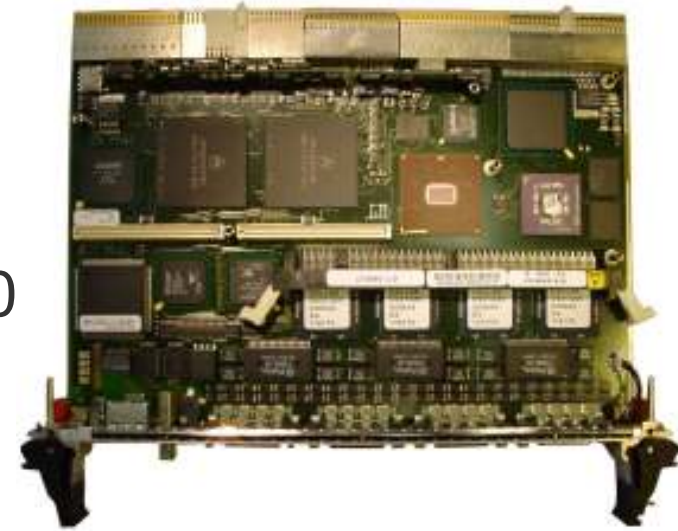
Type 3: single PCB, predominantly digital circuits

- components with high pin count, many BGA's,
 - Most components provide Boundary Scan capabilities.
- ⇒ BScan testing is a “no-brainer”

- **Example:**

only alternative: X-ray inspection, however:

- average investment (in-line AXI): \$300,000
- test execution time: AXI >> BScan test;
430mm x 380mm PCB with 50 BGA's:
 - Inspection by AXI: 75 seconds
 - ~ 10 seconds via BScan
- average costs per test minute calculated as \$1
- production volume of 50,000 PCB's per year,
reduction in test execution time: > \$50,000 savings annually





Is BScan right for you?

What can BScan potentially do for you?

- Simplify your test
- Lower your cost of test
- Improve your test strategy

Let's find out for sure by doing a
Design For Testability analysis

... free of charge [contact info@goepelusa.com]





In-Circuit Test

- + Short test execution
- + Relatively fast test program development
- Expensive test fixtures, maintenance, storage
- New fixtures needed when layout changes
- Typically not available during prototyping
- Test fixtures take weeks to design and build
- Test access limited on modern PCB's





Flying Probe Test

- + No bed-of-nail fixture required
- + Relatively fast test program development
- Very long test execution time
- Modifications of test programs required when layout changes
- Typically not usable in production test
- Test access limited on modern PCB's



Functional Test

- + Very good at-speed test to verify UUT functionality
- Very long test development times (cost!)
- Poor diagnostic capabilities
- Difficult fault isolation
- Test of all functions (to cover all faults) practically impossible



- + Short test execution
- + Fast test program development
- Expensive test fixtures, maintenance, storage
- New fixtures needed when layout changes
- Typically not available during prototyping
- Test fixtures take weeks to design and build
- Test access limited on modern PCB's



AOI / AXI

- + No bed-of-nail fixture required
- + Relatively fast test program development
- + Test of non-electrical properties, such as alignment
- Long test execution time
- No test of electrical properties
- Only visible features can be verified (AOI)
- Very expensive test equipment (AXI)



Boundary Scan / JTAG

- Potential to enhance time to market;
- Available throughout product life cycle;
- Early, easy and fast test development;
- Test for connectivity problems (stuck-at 1/0, open pins, shorted nets);
- Value-adding:
 - In-System Programming,
 - BIST and Debug access,
 - System Test;





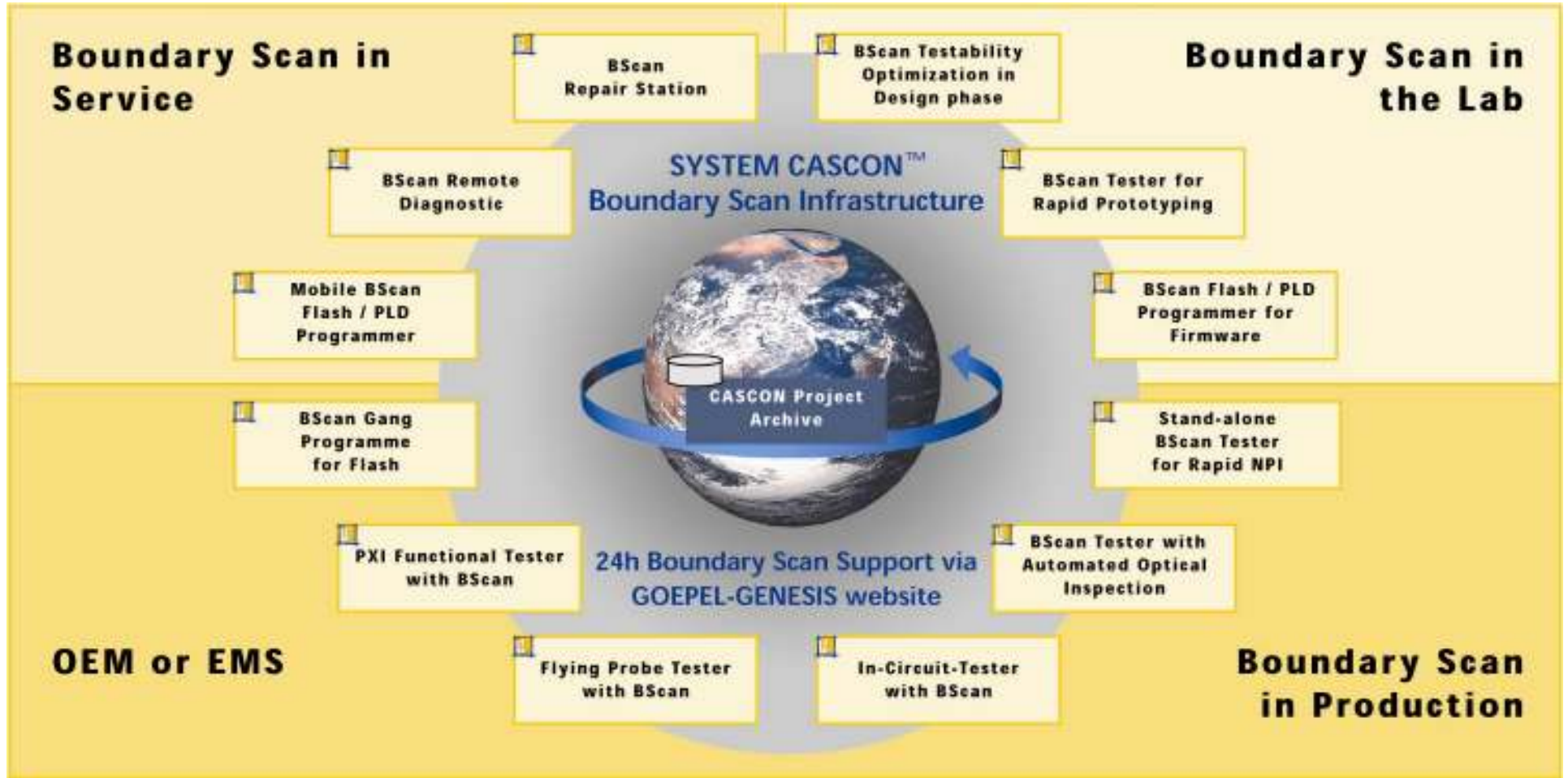
ICT vs. Boundary Scan

	In Circuit Test		Boundary Scan
	bed of nails	Flying Probe	
speed	+	--	0
analog devices (power)	+	++	(-) (IEEE 1149.4)
digital devices	0	(-)	+ (functional description not necessary)
net contacting	- (mechanically)	- (mechanically)	+ (via test bus)
flexibility	--	+	++
costs per new UUT	-- (nail adapter)	0 (test creation)	0 (test creation)
costs for test equipment	-	0	++





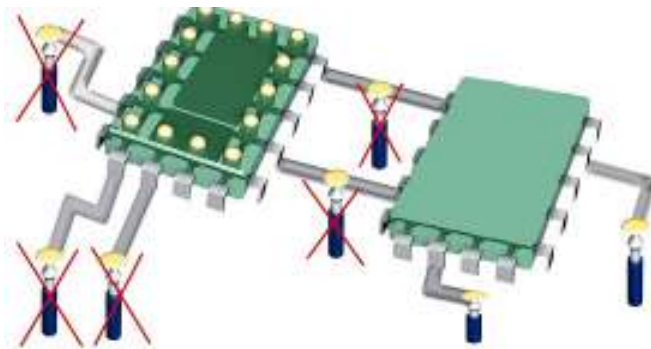
BScan in Product Life Cycle





Boundary Scan / JTAG

- Regain test access (BGA, CSP, etc.)
- Quick test execution;
- Inexpensive test equipment;
- No or very simple test fixture;





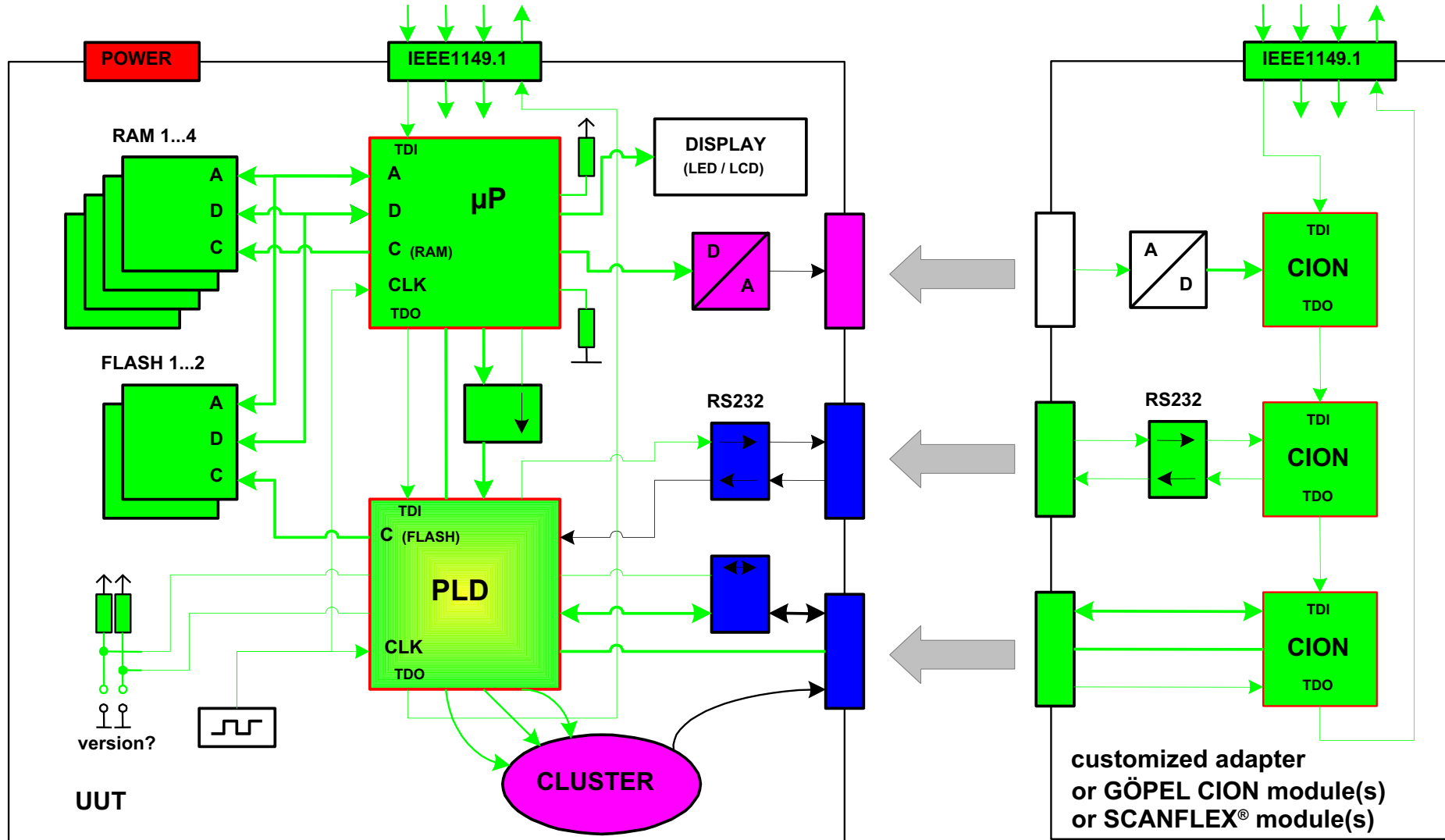
Boundary Scan applications

- Providing test access for ...
 - Checking interconnections
 - Debugging / emulating circuitry
 - Supporting functional test
 - Enabling remote test / verification
- Programming devices
- ...





Extended Boundary Scan



 Testable device

 Boundary Scan compliant device





Limits of Boundary Scan

- IEEE 1149.1 limited to digital interconnect test
- No at-speed test (exception: BIST)



New standards (dot4, dot6, ...)



Combination of Boundary Scan and other Test Methodologies





Fault spectrum

Discussion topics:

What kind of faults do you see most in your production ?

When and how to you test ?

What is your yield ?

What is your slip-through rate ?



Fault spectrum

Test Coverage models for structural defects:

- **MPS** - Philips Research
(Material, Placement, Solder)
- **PPVS** - ASTER Ingénierie
(Presence, Polarity, Value, Solder)
- **PCOLA/SOQ** - Agilent Technologies
(Presence, Correctness, Orientation, Live, Alignment,
Short, Open, Quality)

Of concern for functional test coverage:

- Design defects
- Functional defects



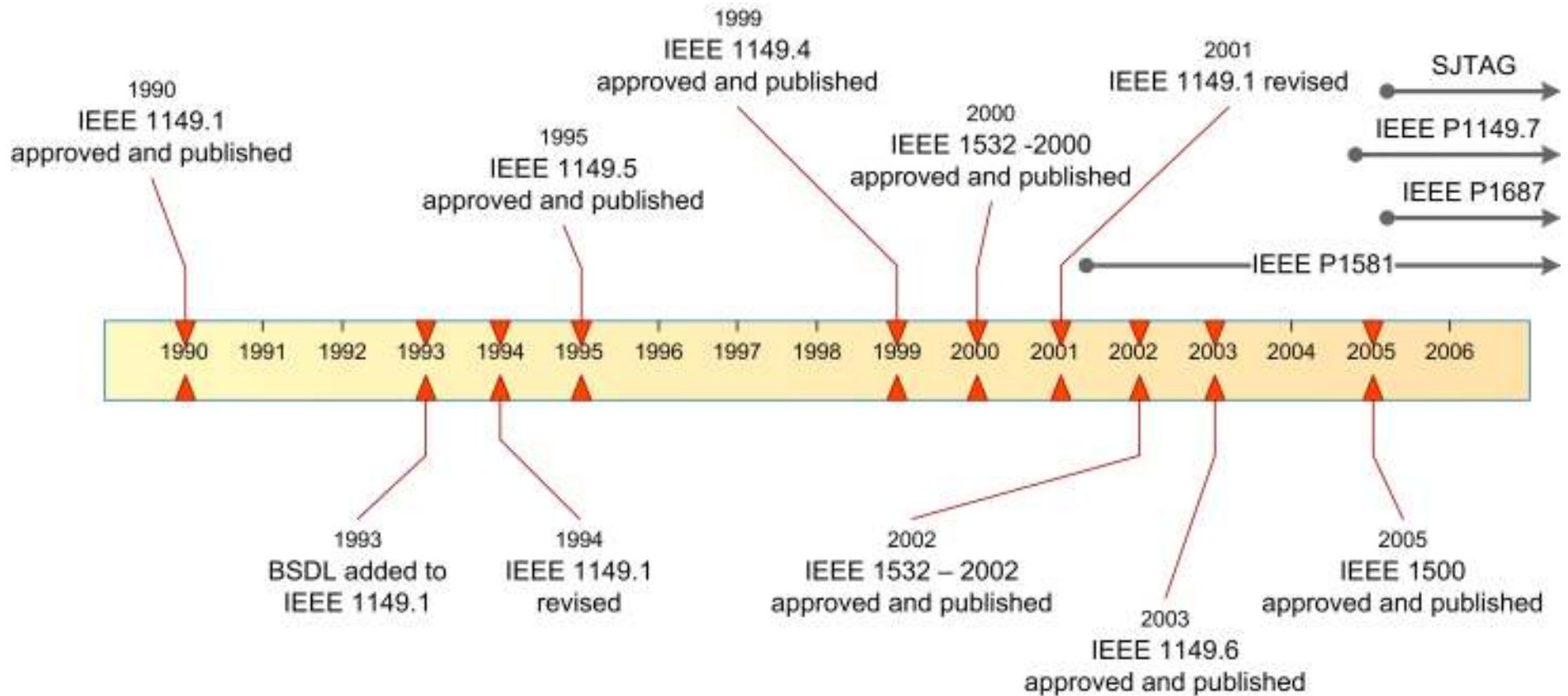
What is Boundary Scan ?





What is Boundary Scan ?

A little bit of history (and outlook) ...





BScan – PCOLA/SQL

Component properties:

- ✓ Presence
- ✓ Correctness (*correct device*)
- ✓ Orientation
- ✓ Live (*the device is basically alive*)
- Alignment (*device is centered, no skews or small rotations*)

Connections:

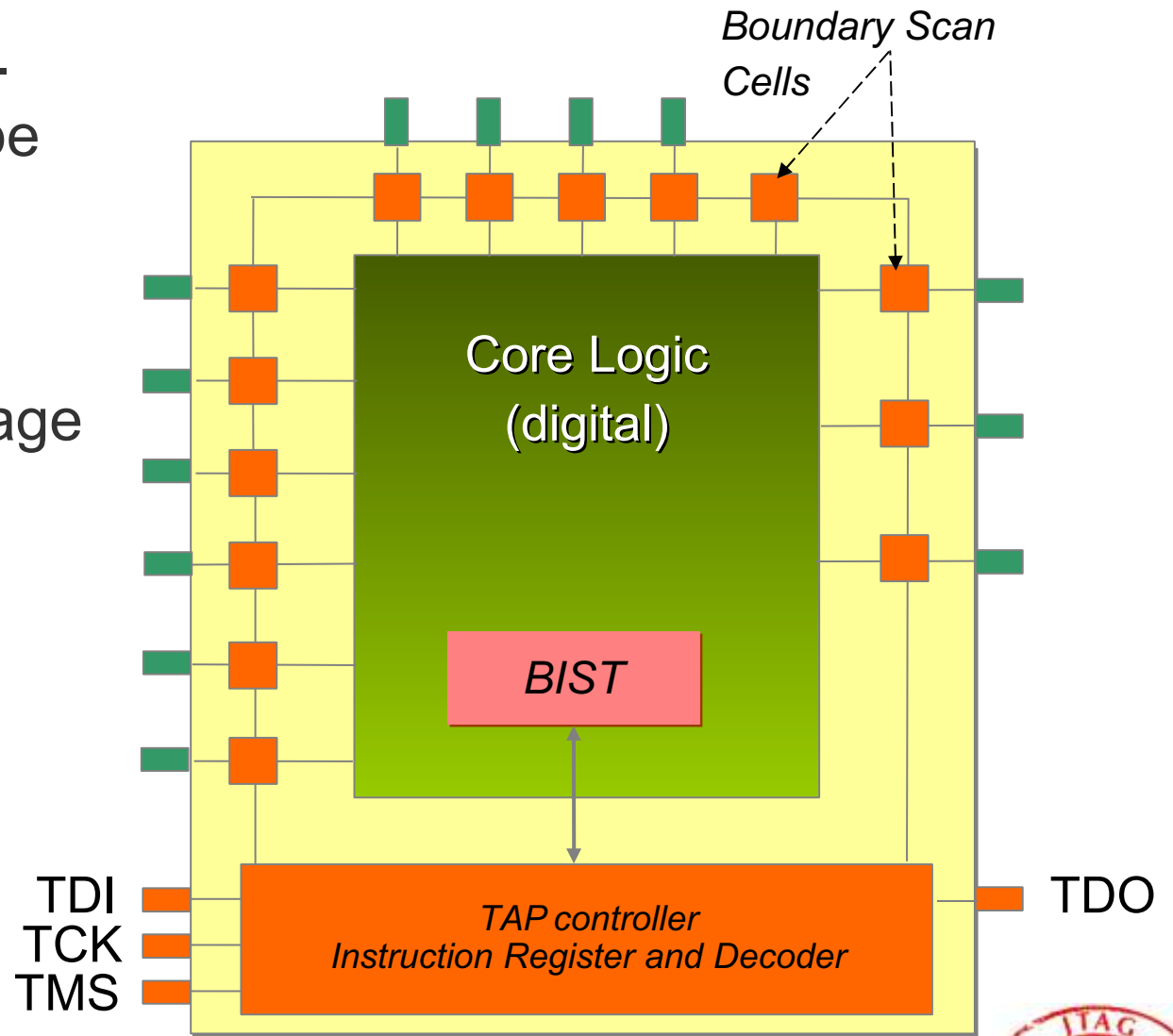
- ✓ Shorts
- ✓ Opens
- Quality



Basics of IEEE 1149.1

IEEE 1149.1 specifies ...

- Test resources to be implemented in devices
- Boundary Scan Description Language (BSDL)





Basics of IEEE 1149.1

Mandatory features:

- Test Access Port (TAP):
TCK, TMS, TDI, and TDO
- TAP Controller
- Instruction Register (2 bit or more)
- Bypass Register (1 bit)
- Boundary Scan Register (1 bit or more)





Basics of IEEE 1149.1

Optional features:

- Fifth Test Access Port (TAP) signal:
/TRST
- IDCode Register (32 bit)
- UserCode Register (32 bit)
- Other via TAP accessible resources
(*such as BIST circuitry,
in-circuit programming controller,
etc.*)





IEEE 1149.1 in practice

Typical applications (*only a few examples*):

- Check for shorts between BScan accessible nets
- Check for opens on a BScan pin
- Check for stuck-at-0/1 faults at a net level
- Check for missing resistors
- Check connections to memory devices
- Detect faults in non-BScan circuit clusters
- Control optical indicators (e.g. LED's)
- Provide easy test access for mixed-signal and functional tests
- Use SAMPLE mode to capture signal pattern





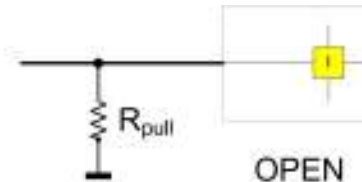
IEEE 1149.1 in practice



OPEN No / No
SA-0/1 No / No
SHORT No / No



OPEN No / No
SA-0/1 Yes / Yes
SHORT Yes / Partial



OPEN Partial / Partial
SA-0/1 Partial / Partial
SHORT Partial / Partial



OPEN Yes / No
SA-0/1 Yes / Partial
SHORT Yes / Yes

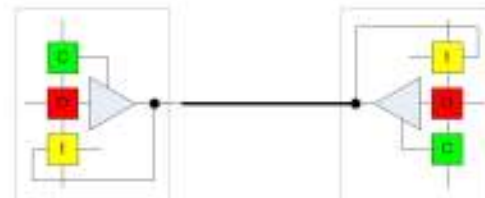


OPEN Yes / No
SA-0/1 Yes / Partial
SHORT Yes / Yes

Detection / Diagnostics



OPEN Yes / No
SA-0/1 Yes / Partial
SHORT Yes / Yes



OPEN Yes / No
SA-0/1 Yes / Yes
SHORT Yes / Yes

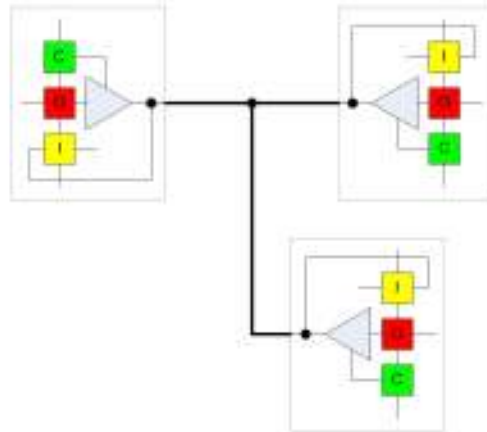




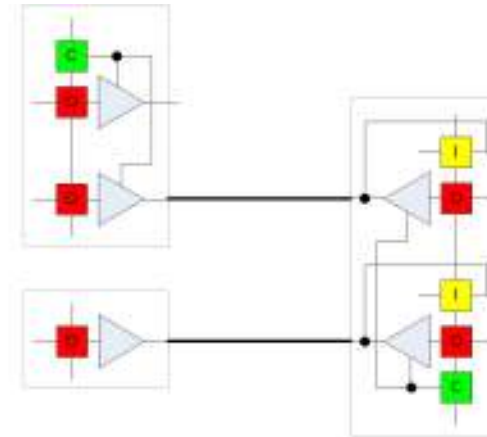
IEEE 1149.1 in practice

Fault detection, diagnostics depend on BScan resources connected to a particular net:

Detection / Diagnostics



OPEN Yes / Yes
SA-0/1 Yes / Yes
SHORT Yes / Yes



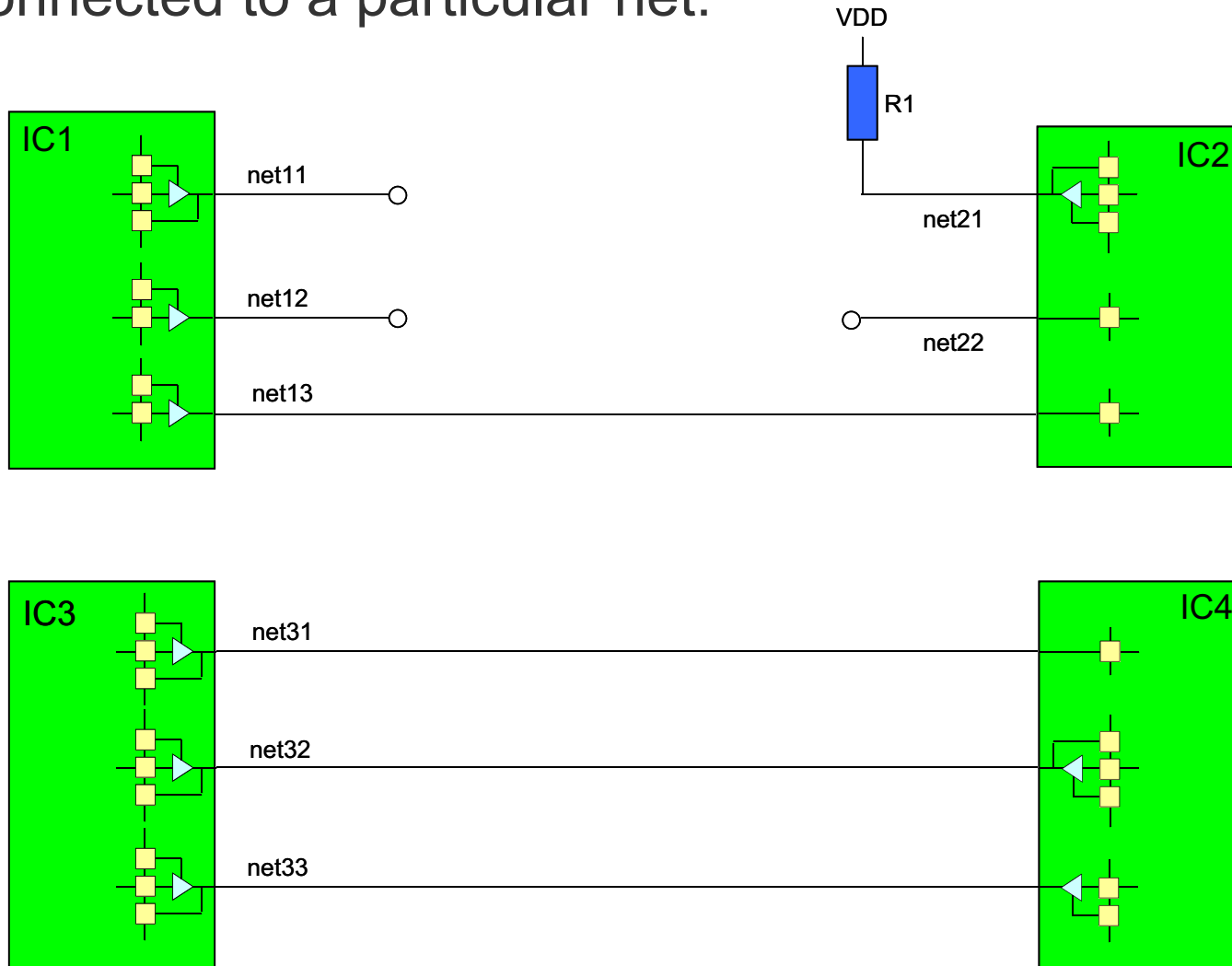
OPEN Yes / Partial
SA-0/1 Yes / Partial
SHORT Yes / Yes





IEEE 1149.1 in practice

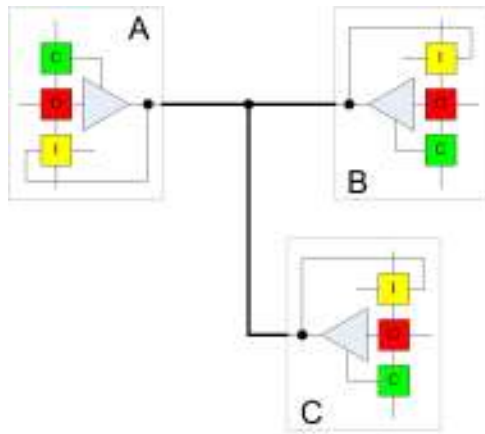
Fault detection, diagnostics depend on BScan resources connected to a particular net:





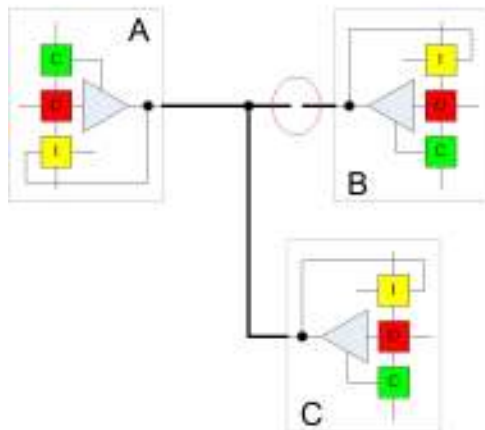
IEEE 1149.1 in practice

Test pattern without and with fault (open pin):



PASS

	A			B			C		
	C	O	I	C	O	I	C	O	I
Preload pattern	L	Z	H	L	Z	H	L	Z	H
A drives, B and C measure	H	L	L	L	Z	L	L	Z	L
A drives, B and C measure	H	H	H	L	Z	H	L	Z	H
B drives, A and C measure	L	Z	L	H	L	L	L	Z	L
B drives, A and C measure	L	Z	H	H	H	H	L	Z	H
C drives, A and B measure	L	Z	L	L	Z	L	H	L	L
C drives, A and B measure	L	Z	H	L	Z	H	H	H	H



FAIL

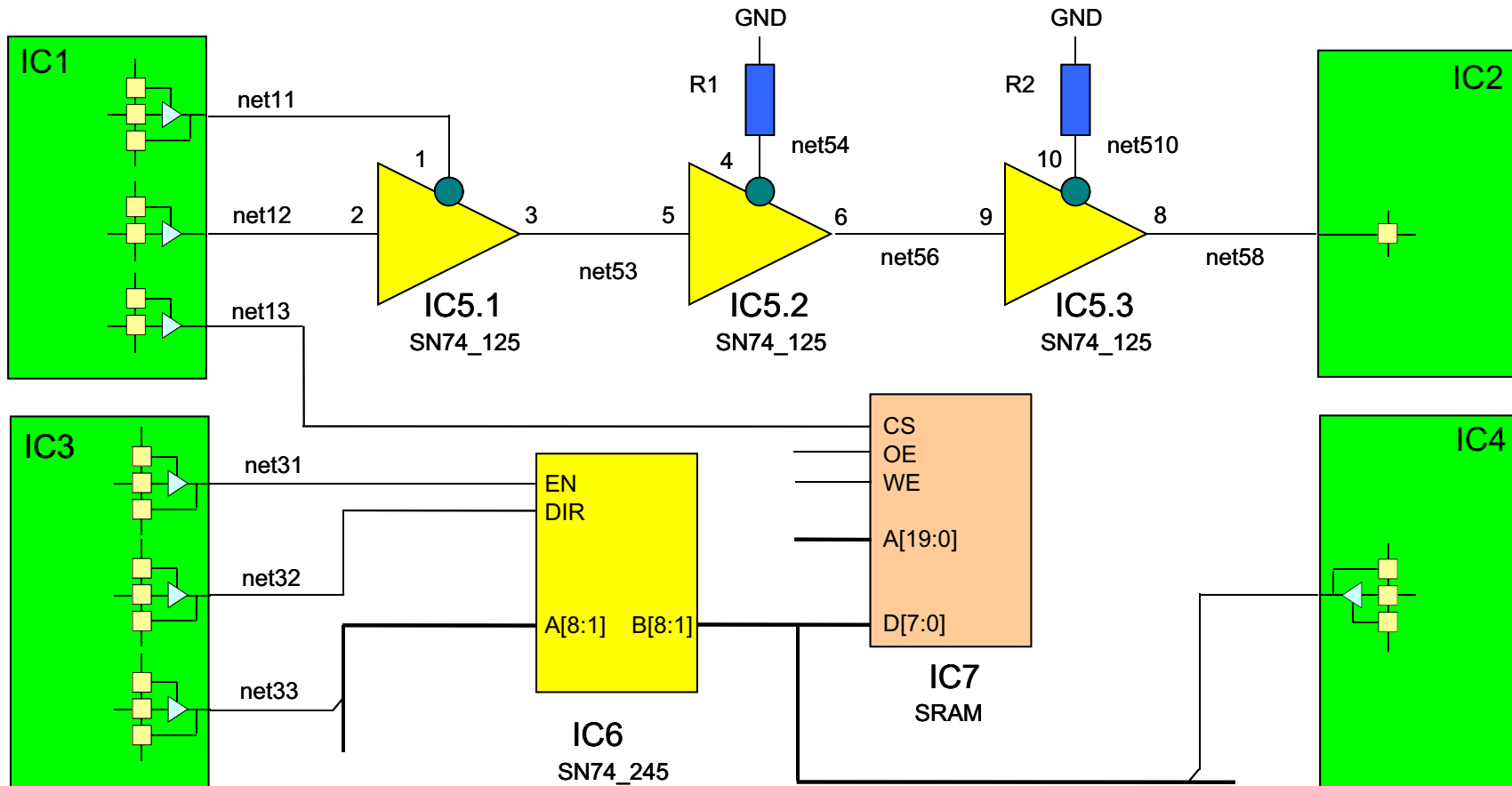
	A			B			C		
	C	O	I	C	O	I	C	O	I
Preload pattern	L	Z	H	L	Z	H	L	Z	H
A drives, B and C measure	H	L	L	L	Z	H	L	Z	L
A drives, B and C measure	H	H	H	L	Z	H	L	Z	H
B drives, A and C measure	L	Z	H	H	L	L	L	Z	H
B drives, A and C measure	L	Z	H	H	H	H	L	Z	H
C drives, A and B measure	L	Z	L	L	Z	H	H	L	L
C drives, A and B measure	L	Z	H	L	Z	H	H	H	H





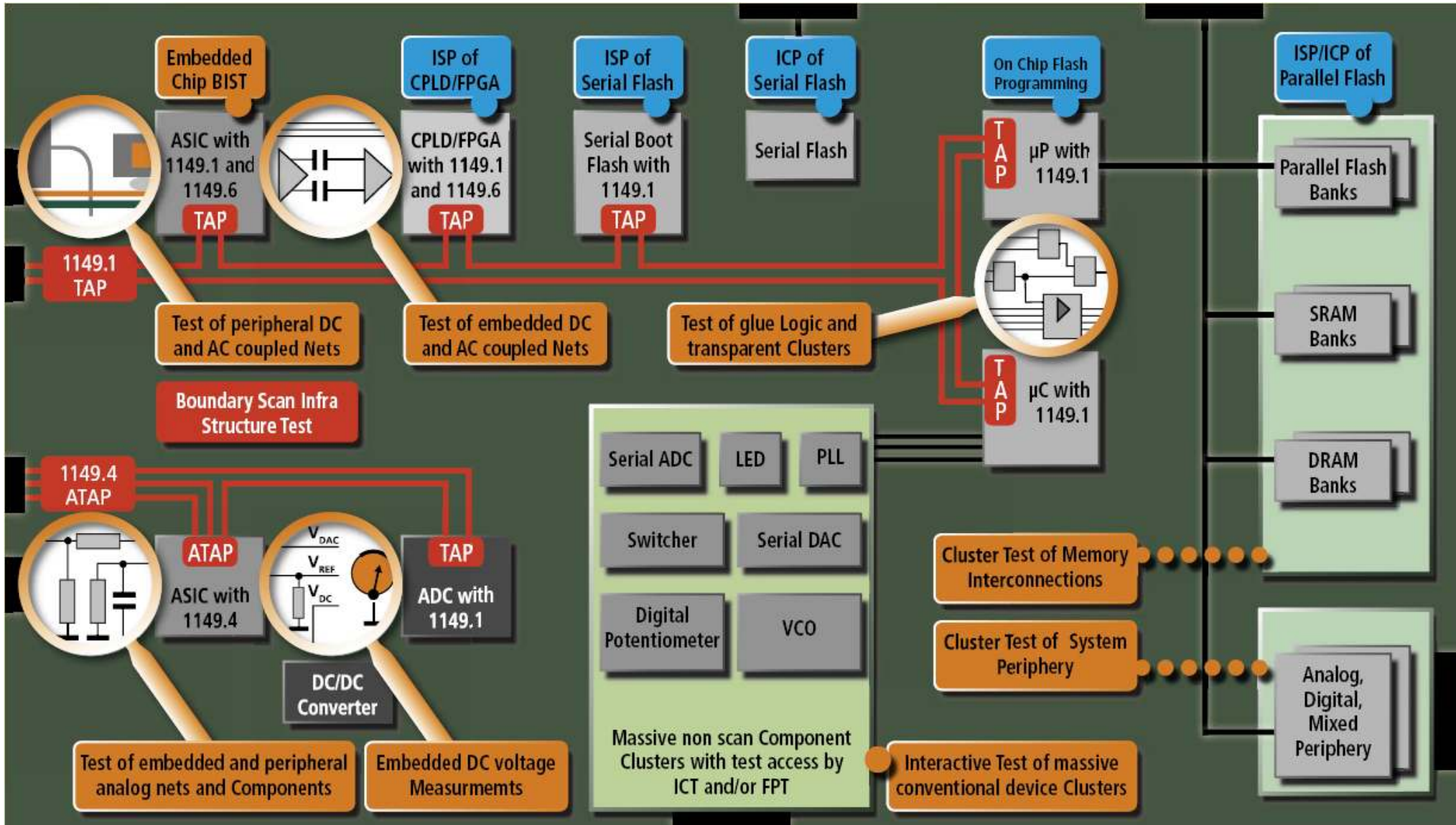
IEEE 1149.1 in practice

How about non-BScan devices?





Board Level applications



ISP = In-System Programming

ICP = In-Circuit Programming

BIST = Built-In Self Test





Board Level applications

- Infrastructure Test
- Interconnection Test
- Memory Cluster Test
- Logic Cluster Test
- Other Cluster Tests
- ISP for FLASH
- ISP for serial EEPROM
- ISP for PLD/FPGA
- BIST
- Emulation, Debugging, Fault Insertion, ...



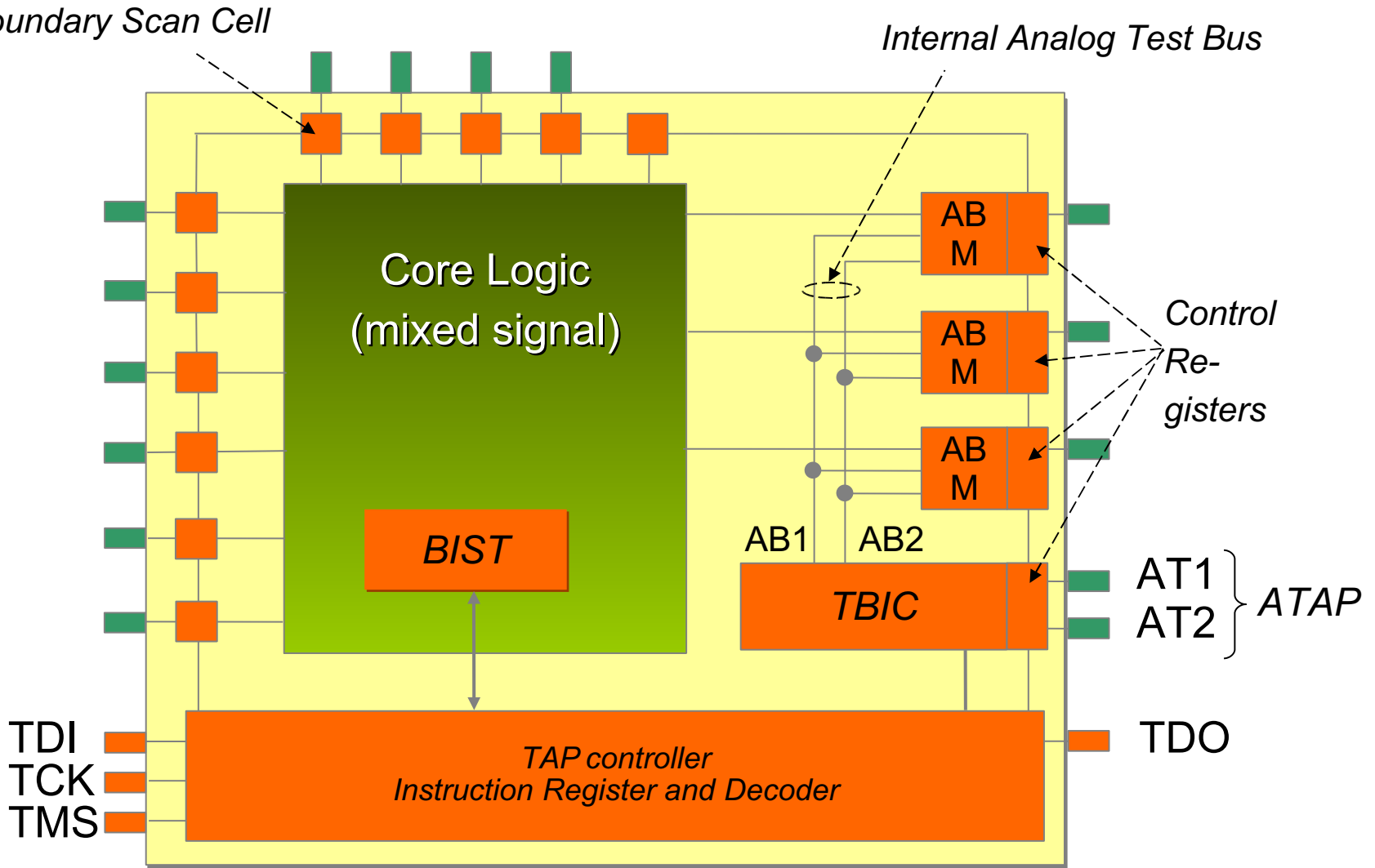
BScan / Functional Test

- Low cost, flexible, powerful
- Very good test coverage, diagnostics:
 - Boundary Scan for structural test
 - Functional Test for parametric and at-speed test
 - BScan for simplified access in functional tests
- Integrated, highly automated test flow
- Combination through API's; off-the-shelf or ad-hoc software





Basics of IEEE 1149.4





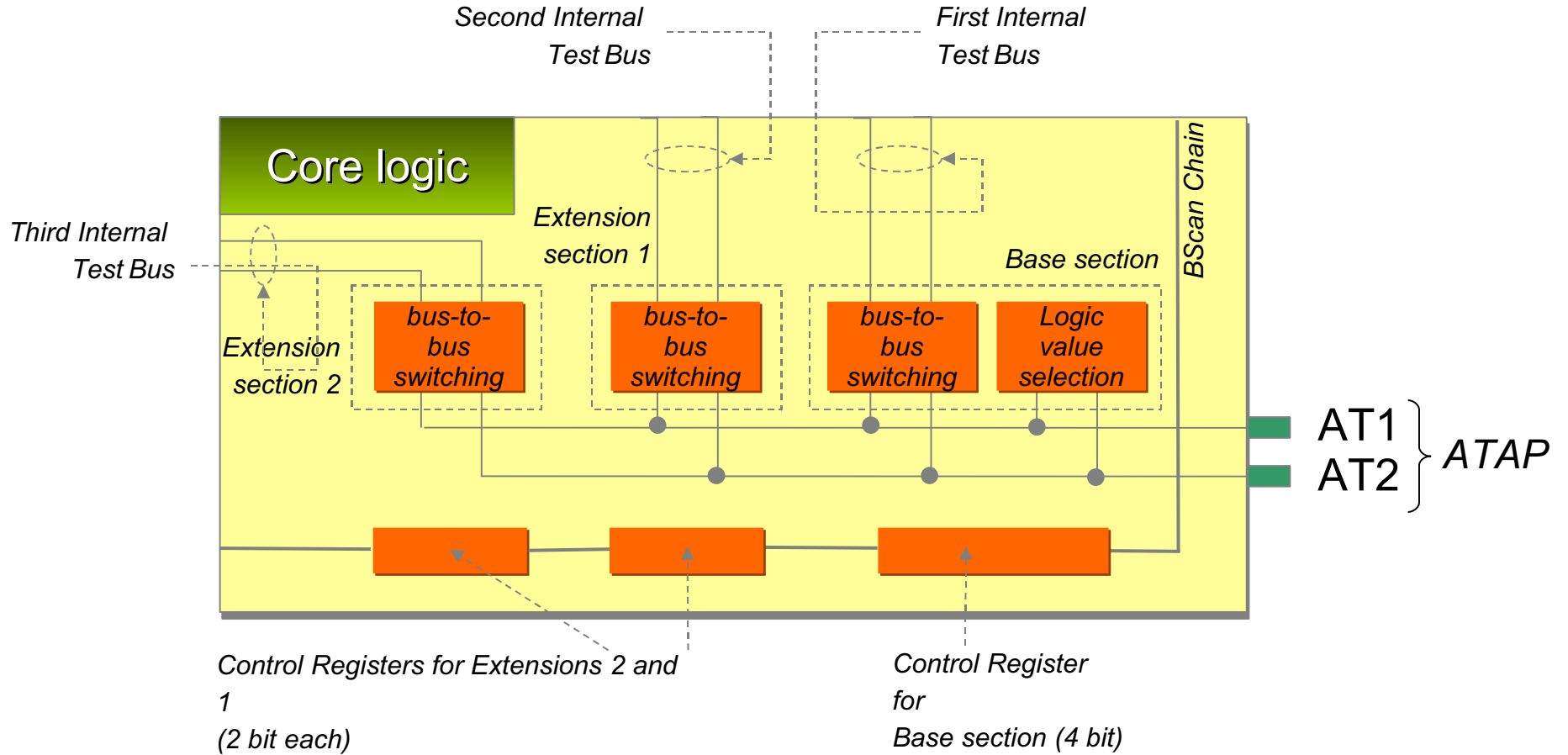
Basics of IEEE 1149.4

- Parametric Test for
 - *Passive components (resistors, capacitors, inductors, etc.) and/or passive elements intrinsic to the interconnect*
 - *Pull- or termination resistors*
 - *Active components (diodes, transistors, sensors, etc.)*
 - *Impedance networks*
- Extended Interconnect Test
- Limited number of devices available
- Emerging tool support



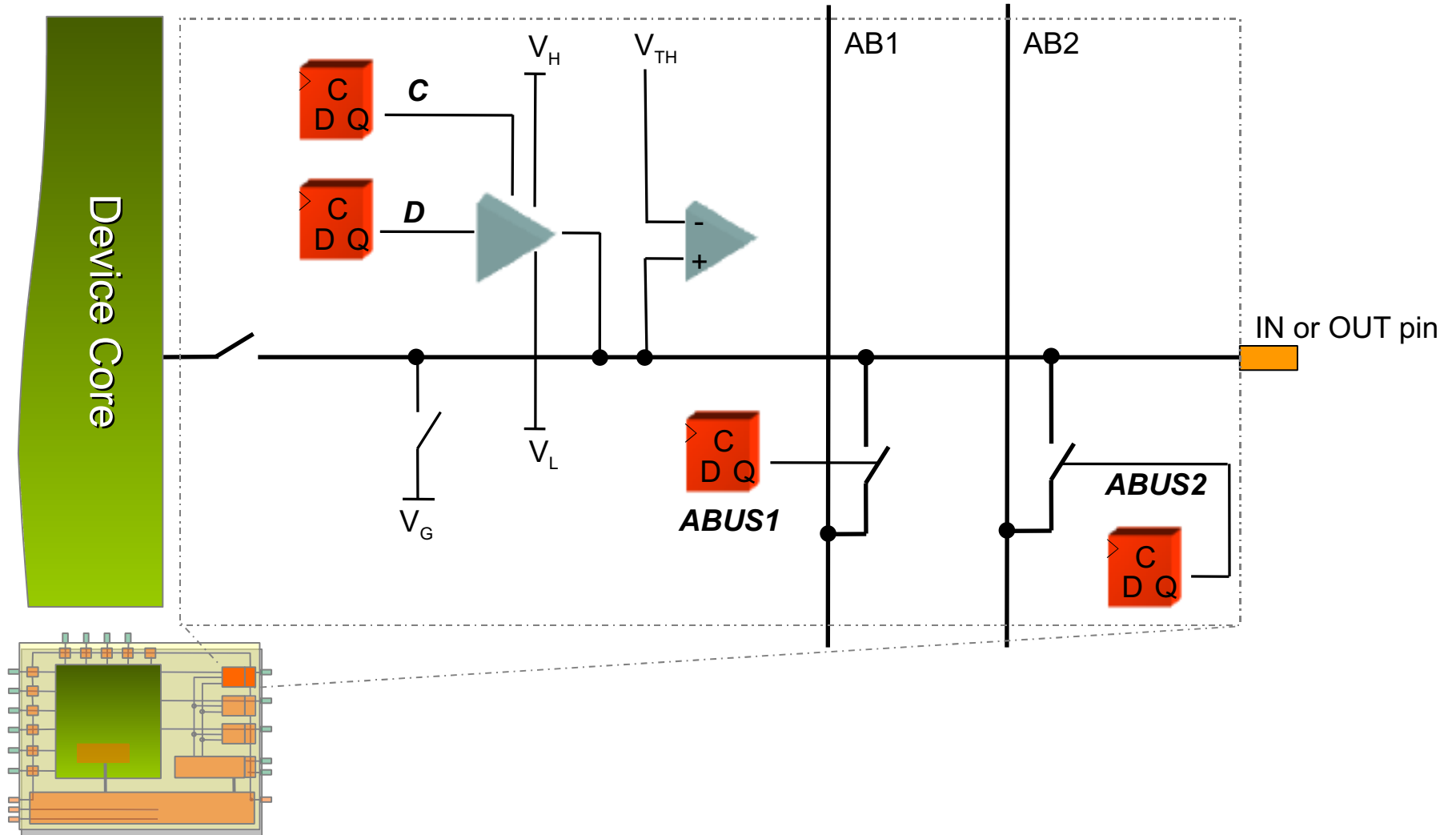


Basics of IEEE 1149.4





Basics of IEEE 1149.4





Basics of IEEE 1149.6

- Extending Interconnect Test to AC-coupled networks
- Standard approved in 2003
- Devices are emerging
- Tool support is available





Purpose of IEEE 1149.6

- Extending IEEE-Std. 1149.1 capabilities by providing test methodology for
 - Differential interconnections
 - AC coupled networks
- Defines hardware structure and two new instructions





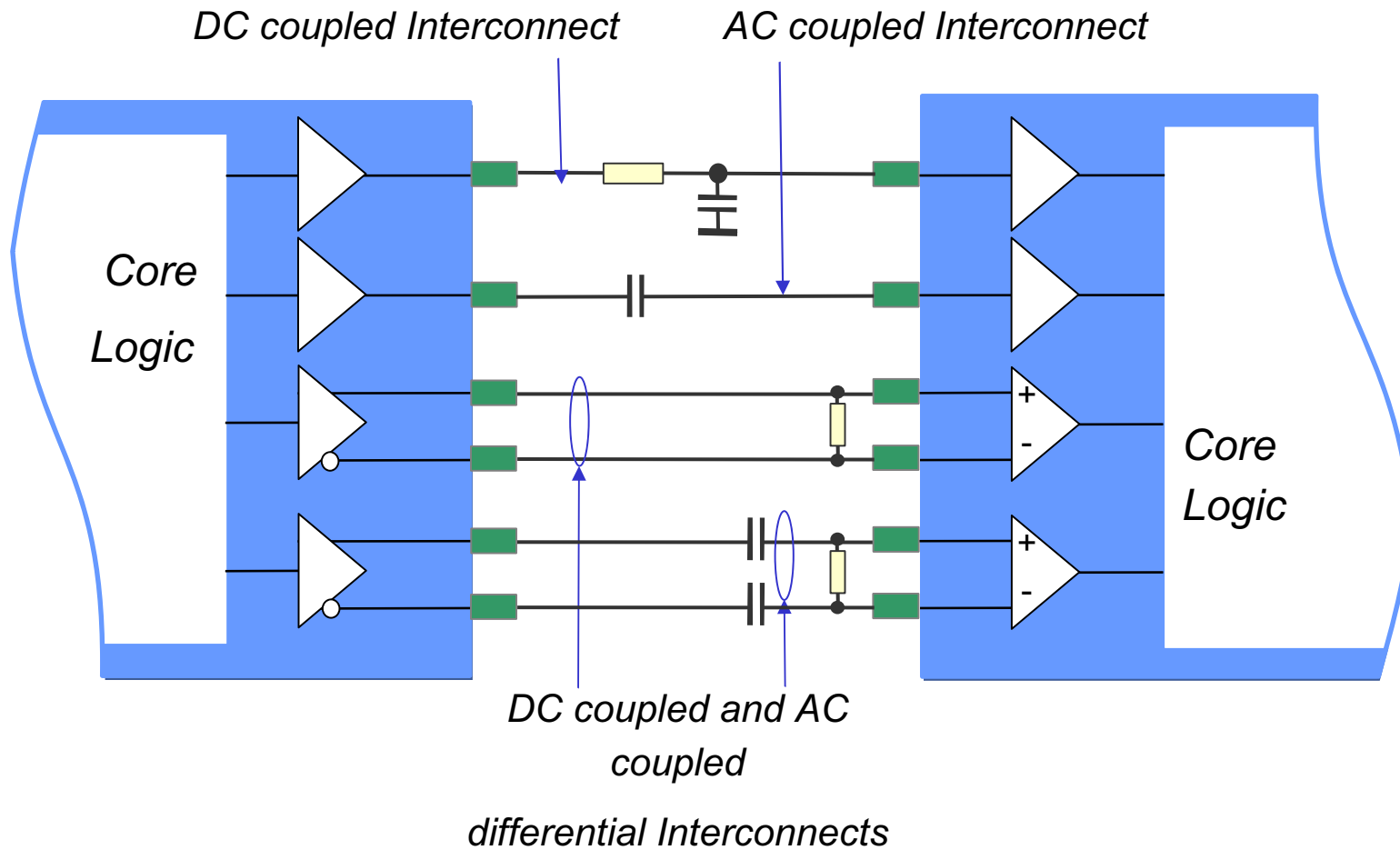
Principle of IEEE 1149.6

- Operates in parallel with 1149.1 and 1149.4
- Proposes a way of testing AC coupled networks by providing AC Test Signal on output and recovering signal on inputs
- Access to test resources through IEEE-1149.1 TAP





Signal coupling



Shown above are just a few sample coupling schemes
Coupling capacities could also be implemented inside the IC





1149.6 Main Features

- A IEEE-1149.6 compliant device is also 1149.1 compliant
- New AC-Test instructions defined in 1149.6:
 - EXTEST_PULSE (mandatory)
 - EXTEST_TRAIN (mandatory)
- AC-pins receiving data have test receiver:
 - Single ended AC-pin: one test receiver
 - Differential channel: two test receiver
- AC outputs use mission driver





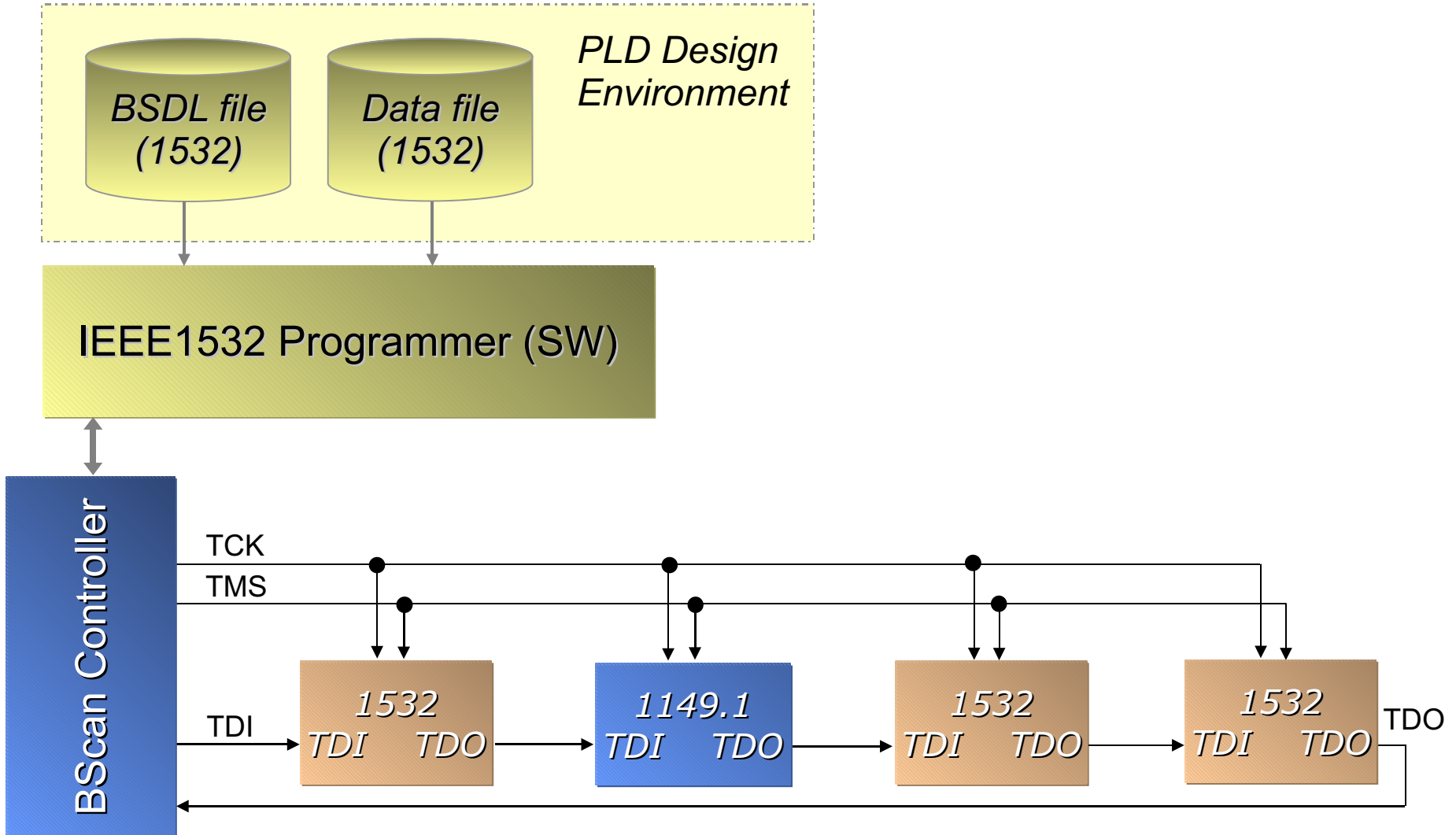
Basics of IEEE 1532

- Standardized in-system programming (ISP) method
- Formal extension to IEEE-1149.1b-1994
- Access to on-chip programming resources via TAP
- Unified programming approach for devices from different vendors
- Concurrent programming of multiple devices from different vendors, reducing cost related to ISP
- Data and programming algorithm in separate files





Basics of IEEE 1532





New standards / initiatives

- IEEE P1581
- IEEE P1149.7 (cJTAG)
- SJTAG
- IEEE P1687 (IJTAG)
- other





Basics of IEEE P1581

- To test connectivity to non-BScan devices easily
- Solve test problems for devices such as DDR-SDRAM, DDR2-SDRAM, FLASH, etc.
 - 1149.1 not built in !
 - Controllability, complexity
 - Test time
 - Test conditions
(use of untested resources to test the DUT)
- Simple, quasi-static interconnect test
(no need for at-speed access or initialization)
- Multiple P1581 devices in bus structure





Basics of IEEE P1581

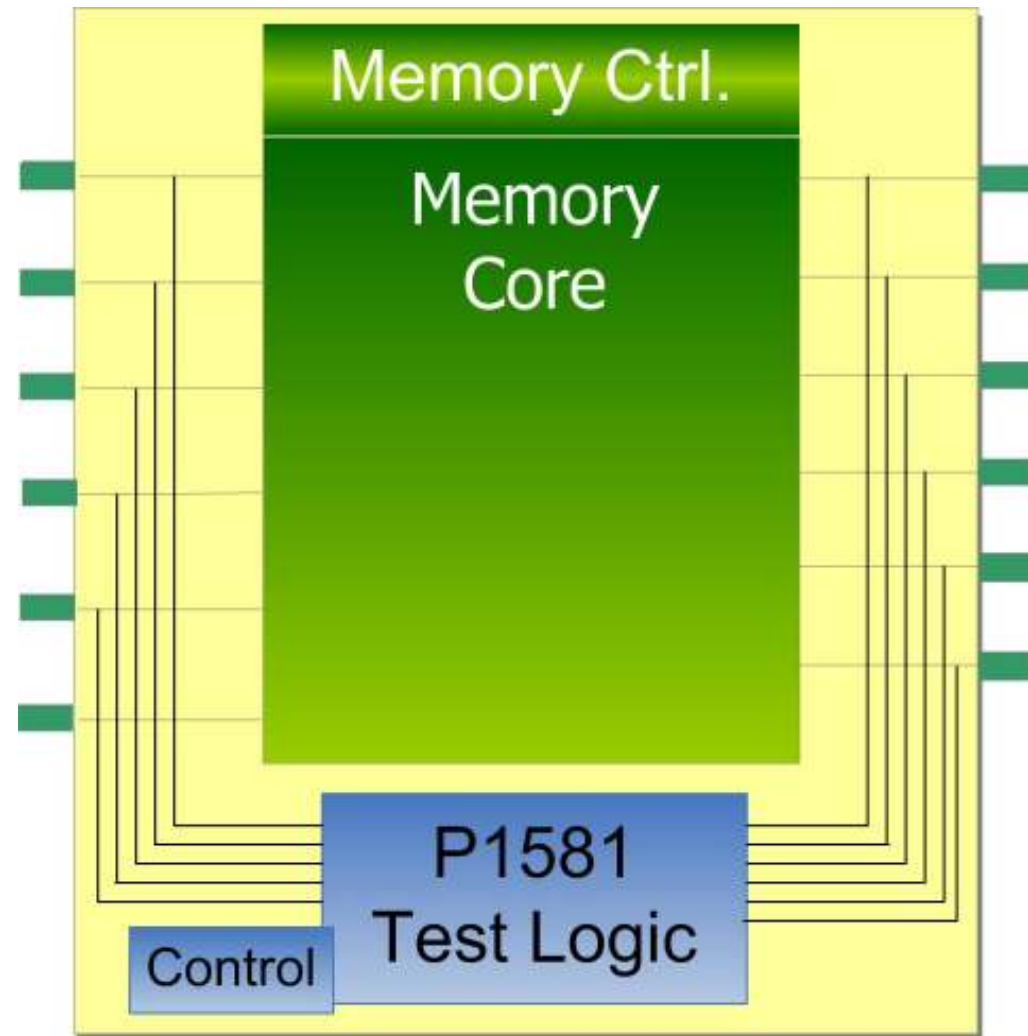
Device is a
“slave”

Test Control:

- Optional Test Pin

Or

- Test Control Circuitry (various proposals)





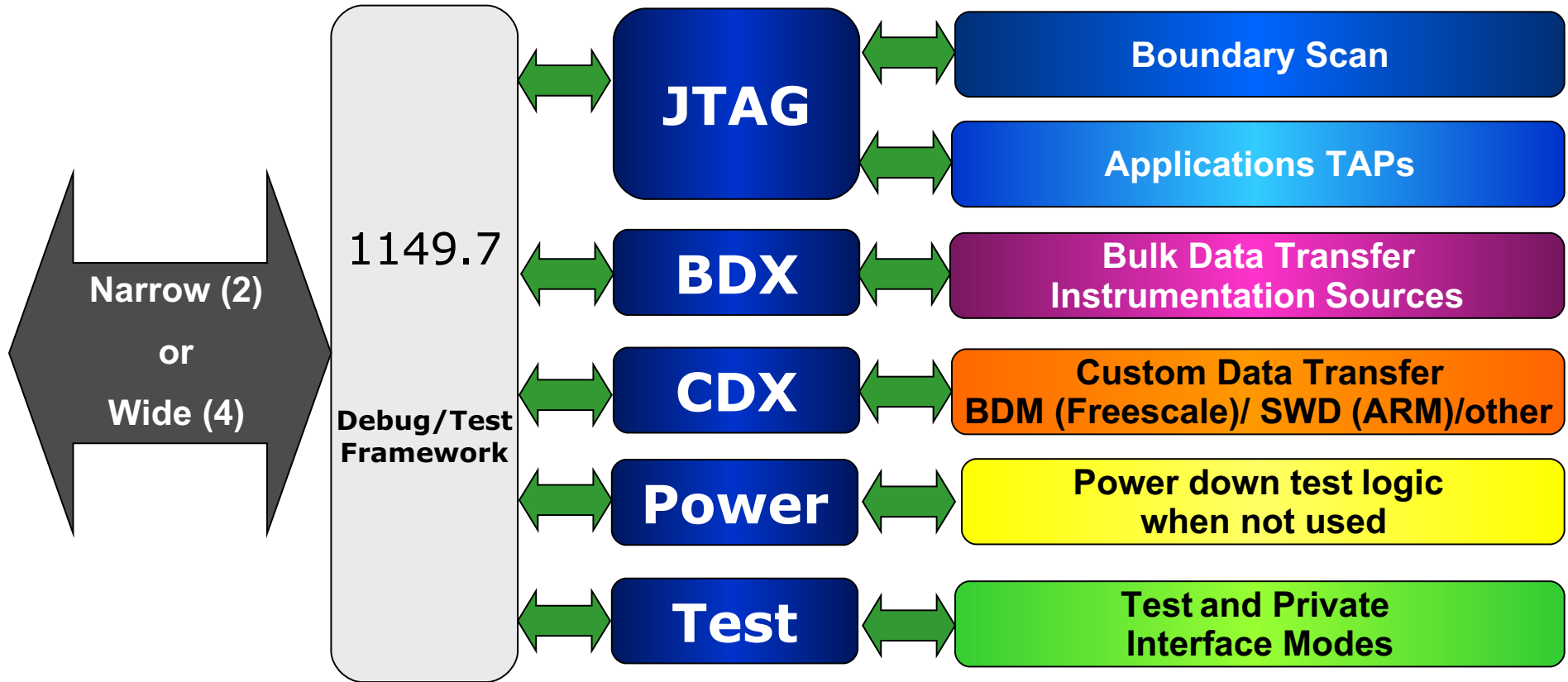
P1581 test logic circuitry

- XOR/XNOR, or Inverters/AND
- Only combinational, non-sequential logic
- Easy to implement, simple test vectors
- Faults on pins don't inhibit test of other pins
- Fault detection guaranteed
- Fault diagnostics depends on implementation, test vectors
- Patented vs. public domain





Basics of IEEE P1149.7



- ◆ IEEE 1149.1 signaling used at start-up
- ◆ SW directed mode switches between JTAG modes and advanced modes
- ◆ SW directed mode switches between JTAG modes and advanced modes. Software drivers always use IEEE state sequences.
- ◆ Framework for multiple debug and other technologies





Basics of IEEE P1687

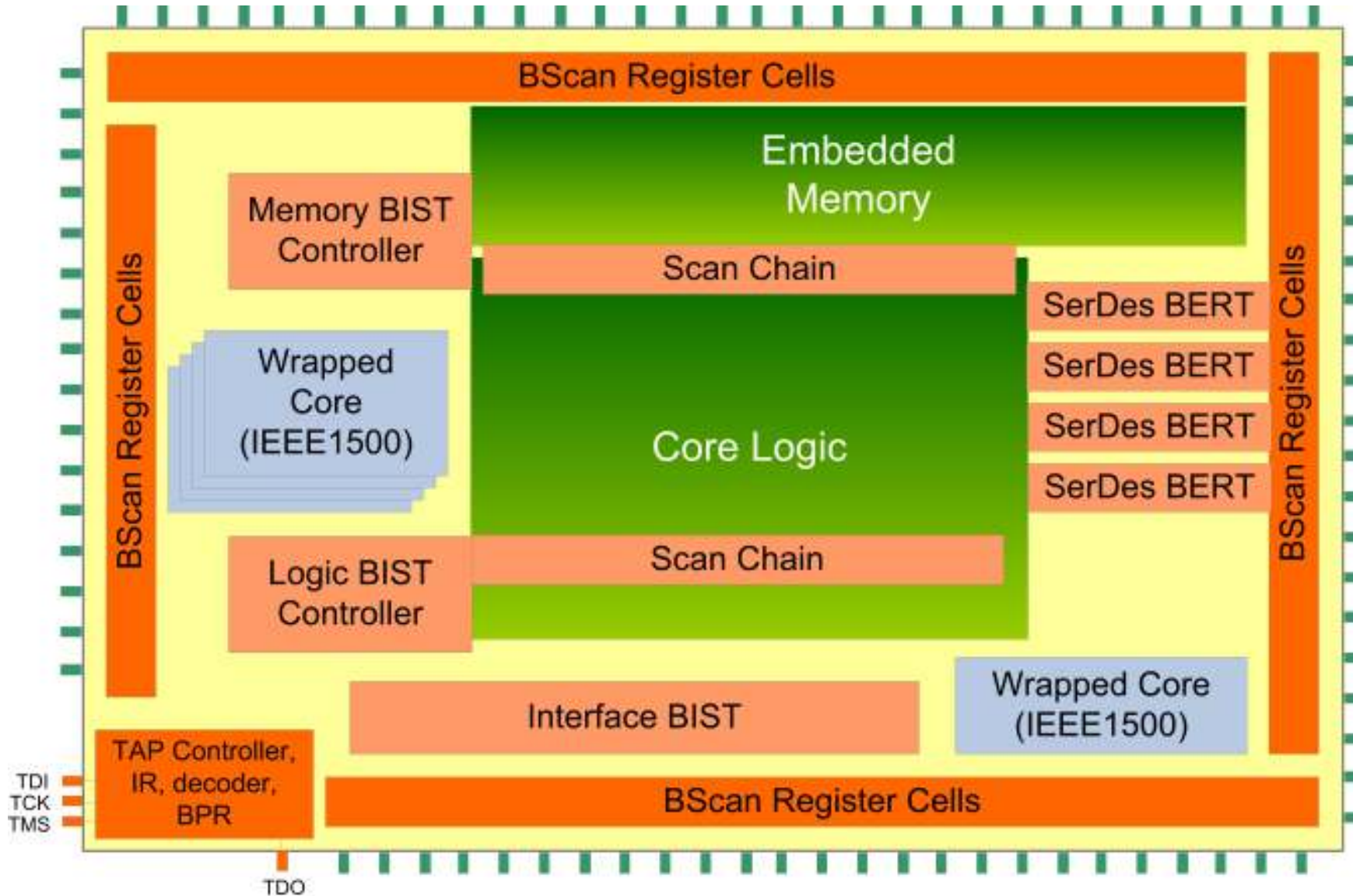
Focus on

- **Documentation:** architectural descriptions
 - Identify accessible embedded instruments,
 - Specify characteristics of the instrument;
- **Access protocols:** procedure descriptions
 - How to communicate with an instrument,
 - Facilitate re-use through portability;
- **“Enhanced”, secondary access/interface:**
 - Access instruments not easily handled solely by the TAP (i.e. use high bandwidth I/O)
 - Simplify hierarchical test architectures





Basics of IEEE P1687





Basics of SJTAG

Goal:

to standardize data contents and formats for communication:

between external Test Manager platforms and internal Embedded Test Controllers,

and

between Embedded Test Controllers and the UUTs they serve

for all variants of XBST and EBST

XBST - external Boundary Scan Test
EBST - embedded Boundary Scan Test





References

Books:

- Boundary Scan Handbook, 3rd Edition, Ken P. Parker, Kluwer Academic Publishers, ISBN 1-4020-7496-4
- Analog and Mixed-Signal Boundary-Scan, Adam Osseiran, Kluwer Academic Publishers, ISBN 0-7923-8686-8
- Digital Systems Testing and Testable Design, Miron Abramovici et.al., IEEE Press, Wiley Interscience, ISBN 0-7803-1093-4

Websites:

- www.goepelusa.com
- www.freeDFT.info
- www.DFTdigest.com

Other publications:

- ITC Proceedings (papers on the topic; there are plenty ...)
- Testability Guidelines, SMTA TP-101C (2002), www.smta.org





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